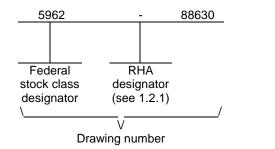
LTR DESCRIPTION DATE (YR-MO-DA) APPROVED  A Changes to slew rate test. Changes IAW NOR 5962-R194-93. 93-08-25 M. A. FRYE  B Changes boilerplate to add one-part numbers. Add device type 03. 97-06-03 R. MONNIN  C Change to group A subgroups for TCVOOS in table I. Update boilerplate rrp 00-10-26 R. MONNIN  D Add device type 01 limits to table I <sub>IB</sub> ro 02-11-22 R. MONNIN  E Drawing updated to reflect current requirements ro 06-05-16 R. MONNIN  F Make changes to the Voos test for device type 03 as specified under Table I 08-07-01 R. HEBER  G Update drawing to current MIL-PRF-38535 requirements rrp 13-02-14 C. SAFFLE	A B	Changes to slew ra		D	FSCRIP1	TION!													
B Changes boilerplate to add one-part numbers. Add device type 03. Add delta test limits. Redrawn.  C Change to group A subgroups for TCVOOS in table I. Update boilerplate rrp  D Add device type 01 limits to table I <sub>IB</sub> ro  E Drawing updated to reflect current requirements ro  Make changes to the VOOS test for device type 03 as specified under Table I and Table IIB ro  R. MONNIN  R. MONNIN  R. MONNIN  R. MONNIN	В	Changes to slew ra				ION						DA	TE (YI	R-MO-[	DA)		APPR	OVE	)
Add delta test limits. Redrawn.  C Change to group A subgroups for TCVOOS in table I. Update boilerplate rrp  D Add device type 01 limits to table I <sub>IB</sub> ro  E Drawing updated to reflect current requirements ro  Make changes to the VOOS test for device type 03 as specified under Table I and Table IIB ro  R. MONNIN  R. MONNIN  R. MONNIN  R. MONNIN  R. MONNIN			ate test.	Chang	es IAW N	IOR	5962-	R194-9	3.				93-0	8-25			M. A.	FRYE	:
D Add device type 01 limits to table I <sub>IB</sub> ro 02-11-22 R. MONNIN  E Drawing updated to reflect current requirements ro 06-05-16 R. MONNIN  F Make changes to the V <sub>OOS</sub> test for device type 03 as specified under Table I 08-07-01 R. HEBER	C				art numbe	ers.	Add d	evice ty	/pe 03.				97-0	06-03		R. MONNIN		i	
E Drawing updated to reflect current requirements ro  Make changes to the V <sub>OOS</sub> test for device type 03 as specified under Table I and Table IIB ro  06-05-16  R. MONNIN  R. HEBER		Change to group A	subgro	ups for	TCVOOS	s in ta	able I.	Updat	e boile	plate.	- rrp	00-10-26		R. MONNIN		l			
F Make changes to the V <sub>OOS</sub> test for device type 03 as specified under Table I 08-07-01 R. HEBER	D	Add device type 01	l limits to	o table I	I <sub>IB</sub> ro								02-1	1-22		R. MONNIN		ł	
and Table IIB ro	Е	Drawing updated to	o reflect	·							06-05-16				R. M	NINNC	i		
G Update drawing to current MIL-PRF-38535 requirementsrrp 13-02-14 C. SAFFLE	F	Make changes to the and Table IIB ro	he V <sub>OO</sub> s					ed unde	er Table	e I		08-0	7-01			R. H	EBER		
	G	Update drawing to	current	MIL-PR	F-38535	requ	iireme	ntsrr	р				13-0	2-14			C. SA	AFFLE	
THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.  REV SHEET	REV SHEET	FIRST SHEET OF T	'HIS DR	AWING	HAS BE	EN F	REPL/	ACED.											
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REV STATUS REV G G G G G G G G G G	THIS DRAWING FOR US DEPAR' AND AGENO	G IS AVAILABLE E BY ALL TMENTS CIES OF THE	APPROVED BY MICHAEL A. FRYE  DRAWING APPROVAL DATE 88-09-13			MICROCIRCUIT, LINEAR, INSTRUMENTATION AMPLIFIER, MONOLITHIC SILICON						1							
REV STATUS OF SHEETS SHEET 1 2 3 4 5 6 7 8 9 10 11 12  PMIC N/A  PREPARED BY CHARLES E. BESORE  THIS DRAWING  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DRAWING APPROVAL DATE  REV G G G G G G G G G G G G G G G G G G G	AMS	C N/A	REVIS	SION LI	EVEL G				l							5962-	8863	0	
REV   G   G   G   G   G   G   G   G   G					J				SHEI		<u> </u>		OF	12					

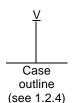
# 1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.
  - 1.2 PIN. The PIN is as shown in the following examples.

For device classes M and Q:

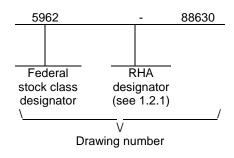


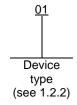


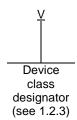


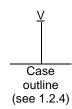


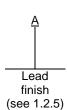
For device class V:











- 1.2.1 <u>RHA designator</u>. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
  - 1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	AMP-01A	Low-noise, precision, instrumentation amplifier
02	AMP-01B	Low-noise, precision, instrumentation amplifier
03	AMP01	Low-noise, precision, instrumentation amplifier

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

Device class	Device requirements documentation
М	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

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1.2.4 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
K	GDFP2-F24 or CDFP3-F24	24	Flat pack
V	GDIP1-T18 or CDIP2-T18	18	Dual-in-line
3	CQCC1-N28	28	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 1/

Supply voltage (V <sub>S</sub> )	±18 V dc
Power dissipation (P <sub>D</sub> )	
Common mode input voltage  Differential input voltage:	Supply voltage
$R_G \ge 2 \text{ k}\Omega$	±20 V dc
$R_G < 2 \text{ k}\Omega$	±10 V dc
Output short circuit duration	Indefinite
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 60 seconds)	+300°C
Thermal resistance, junction-to-case ( $\theta_{JC}$ )	See MIL-STD-1835
Thermal resistance, junction-to-ambient ( $\theta_{JA}$ ):	
Case V	120°C/W
Case 3	104°C/W
Case K	69°C/W
Recommended operating conditions.	

Supply voltage (V <sub>S</sub> )	±15 V dc
Ambient operating temperature range (T <sub>A</sub> )	-55°C to +125°C

<sup>2/</sup> Must withstand the added PD due to short circuit test, e.g., IOS.

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Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

#### 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

### DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

### DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

#### DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <a href="https://assist.dla.mil/quicksearch/">https://assist.dla.mil/quicksearch/</a> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.
  - 3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.2.3 <u>Radiation exposure circuit</u>. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.
- 3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

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	TA	ABLE I. Electrical performance	characteristic	<u>s</u> .			
Tool	C: mah al	Conditions 1/	Group A	Device	Lir	mits	Unit
Test	Symbol	-55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	subgroups	type	Min	Max	Unit
Input bias current			1	01, 03		±4	nA
	I <sub>B</sub>		2, 3			±10	
	l 'B		1	02		±6	
			2, 3			±15	
Input offset current			1	01, 03		1	nA
	I <sub>IO</sub>		2, 3			3	
	110		1	02		2	
			2, 3			6	
Offset referred to input vs. positive supply	+PSR	V+ = +5 V to +15 V, V- = -15 V, G = 1000	1, 2, 3	01, 03	120		dB
		V+ = +5 V to +15 V, V- = -15 V, G = 100			110		
		V+ = +5 V to +15 V, V- = -15 V, G = 10			95		
		V+ = +5 V to +15 V, V- = -15 V, G = 1			75		_
		V+ = +5 V to +15 V, V- = -15 V, G = 1000		02	110		
		V+ = +5 V to +15 V, V- = -15 V, G = 100			100		
		V+ = +5 V to +15 V, V- = -15 V, G = 10			90		1
		V+ = +5 V to +15 V, V- = -15 V, G = 1			70		
Offset referred to input vs. negative supply	-PSR	V- = -5 V to -15 V, V+ = +15 V, G = 1000	1, 2, 3	All	105		dB
		V- = -5 V to -15 V, V+ = +15 V, G = 100			90		
		V- = -5 V to -15 V, V+ = +15 V, G = 10			70		
		V- = -5 V to -15 V, V+ = +15 V, G = 1			50		

See footnote at end of table.

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TABLE I. <u>Electrical performance characteristics</u> – Continued.

<b>.</b>	Symbol	Conditions 1/	Group A	Device	Limits		Linit
Test  Common mode rejection		$-55^{\circ}C \le T_A \le +125^{\circ}C$ unless otherwise specified	subgroups	type	Min	Max	- Unit
Common mode rejection	CMR	$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 1000	1	01, 03	125		dB
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 100			120		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, $G = 10$			100		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, $G = 1$			85		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, $G = 1000$	2, 3		120		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, $G = 100$	-		115		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 10			95		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 1			80		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 1000	2, 3	02	115		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 100			110		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 10			95		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 1			75		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 1000			110		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 100			105		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 10			90		
		$V_{CM} = \pm 10 \text{ V}, 1 \text{ k}\Omega$ source imbalance, G = 1			75		

See footnote at end of table.

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TABLE I. <u>Electrical performance characteristics</u> – Continued.

Test	Symbol	Conditions $\underline{1}/$ -55°C $\leq$ T <sub>A</sub> $\leq$ +125°C	Group A	Device	Lir	mits	Unit
Test	Symbol	unless otherwise specified	subgroups	type	Min	Max	O mic
Gain equation accuracy	GE	$G = 20R_S / R_G, T_A = +25^{\circ}C$	1	01		0.6	%
		Accuracy measured at G = 1, 10, 100, and 1000		02, 03		0.8	
Gain range	G	T <sub>A</sub> = +25°C	1	All	1	1000	V/V
Output short circuit	I <sub>OS+</sub>	T <sub>A</sub> = +25°C	1	All	60	120	mA
Current	I <sub>OS</sub> -				-120	-60	
Reference input Resistance	R <sub>INREF</sub>	T <sub>A</sub> = +25°C	1	All	35	65	kΩ
Quiescent current	IQ	+V linked to +V <sub>OP</sub> -V linked to -V <sub>OP</sub>	1, 2, 3	All		4.8	mA
Input offset voltage	V <sub>IOS</sub>		4	01		50	μV
			5, 6			80	
			4	02, 03		100	
			5, 6			150	
Output offset voltage	Voos		4	01		3	mV
			5, 6			6	
			4	02		6	
			5, 6			10	
			4, 5, 6	03		10	
Output offset voltage	TOV	5	8	01, 03		50	μV/°C
drift	TCV <sub>OOS</sub>	R <sub>G</sub> = ∞		02		120	

See footnote at end of table.

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TABLE I. <u>Electrical performance characteristics</u> – Continued.

Test	Cymphol	Conditions $\underline{1}$ / ymbol $-55^{\circ}\text{C} \leq \text{T}_{\text{A}} \leq +125^{\circ}\text{C}$		Device type	Limits		Unit
rest	Symbol $-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le +125^{\circ}\text{C}$ unless otherwise specified	subgroups	Min		Max	Offic	
Output voltage swing	Vo	$R_L = 500 \Omega, 2 k\Omega$	4	All	±13		V
		R <sub>L</sub> = 50 Ω			±2.5		
		$R_L = 500 \Omega, 2 k\Omega$	5, 6		±12		
Slew rate	SR	G = 10	4	01	3.5		V/μs
			5, 6		2.75		
			4	02, 03	3.0		
			5, 6		2.0		
Average input offset	TCV	T. 550C 14250C	8	01	0.3		μV/°C
voltage drift	TCV <sub>IOS</sub>	T <sub>A</sub> = -55°C, +125°C	0	02, 03	1.0		μν/ Ο

 $\underline{1}/\ \ V_S=\pm 15\ V,\ R_S=10\ k\Omega,\ R_L=2\ k\Omega,$  unless otherwise specified.

- 3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M.</u> For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.
- 3.9 <u>Verification and review for device class M.</u> For device class M, DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M.</u> Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

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Device types	01 ar	03	
Case outlines	V	К	
Terminal number		Terminal symbol	
1	R <sub>G</sub>	NC	R <sub>G2</sub>
2	$R_{G}$	R <sub>G</sub>	R <sub>G1</sub>
3	-IN	R <sub>G</sub>	-IN
4	V <sub>OOS</sub> NULL	-IN	NC
5	V <sub>OOS</sub> NULL	NC	V <sub>OOS</sub> NULL
6	TEST PIN	V <sub>OOS</sub> NULL	NC
7	SENSE	NC	V <sub>OOS</sub> NULL
8	REFERENCE	V <sub>OOS</sub> NULL	TEST PIN
9	OUTPUT	NC	NC
10	-V <sub>OP</sub>	TEST PIN	NC
11	V-	NC	SENSE
12	V+	SENSE	REFERENCE
13	+V <sub>OP</sub>	REFERENCE	OUTPUT
14	R <sub>S</sub>	OUT	-V <sub>OP</sub>
15	R <sub>S</sub>	NC	NC
16	V <sub>IOS</sub> NULL	-V <sub>OP</sub>	V-
17	V <sub>IOS</sub> NULL	NC	V+
18	+IN	V-	+V <sub>OP</sub>
19		V+	NC
20		NC	R <sub>S2</sub>
21		+V <sub>OP</sub>	R <sub>S1</sub>
22		R <sub>S</sub>	V <sub>IOS</sub> NULL
23		R <sub>S</sub>	V <sub>IOS</sub> NULL
24		NC	+IN
25		V <sub>IOS</sub> NULL	
26		V <sub>IOS</sub> NULL	
27		NC	
28		+IN	

FIGURE 1. <u>Terminal connections</u>.

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### 4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

### 4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
  - (2)  $T_A = +125^{\circ}C$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.

## 4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.
- 4.3 <u>Qualification inspection for device classes Q and V.</u> Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

## 4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 7, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1, 2, 3, 4, 5, <u>1</u> / 6, 8	1, 2, 3, 4, <u>1</u> / 5, 6, 8	1, 2, 3, <u>1</u> / <u>2</u> / 4, 5, 6, 8
Group A test requirements (see 4.4)	1, 2, 3, 4, 5, 6, 8	1, 2, 3, 4, 5, 6, 8	1, 2, 3, 4, 5, 6, 8
Group C end-point electrical parameters (see 4.4)	1	1	1 <u>2</u> /
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)			

<sup>1/</sup> PDA applies to subgroup 1.

Table IIB. 240 hour burn-in and group C end-point electrical parameters.

Doromotor	Davisa tura	Li	imit	De	elta
Parameter	Device type	Min	Max	Min	Max
V <sub>IOS</sub>	01		50 μV		40 μV
	03		100 μV		40 μV
Voos	01		3 mV		6 mV
	03		10 mV		10 mV
I <sub>B+</sub>	01, 03		4 nA		3 nA
I <sub>B-</sub>	01, 03		4 nA		3 nA

## 4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

## 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b.  $T_A = +125$ °C, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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Delta limits in accordance with table IIB shall be computed with reference to the previous interim electrical parameters.

- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
  - 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).
  - a. End-point electrical parameters shall be as specified in table IIA herein.
  - b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25$ °C, after exposure, to the subgroups specified in table IIA herein.

# 5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

### 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.
  - 6.6 Sources of supply.
- 6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.
- 6.6.2 <u>Approved sources of supply for device class M.</u> Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

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### STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 13-02-14

Approved sources of supply for SMD 5962-88630 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <a href="http://www.landandmaritime.dla.mil/Programs/Smcr/">http://www.landandmaritime.dla.mil/Programs/Smcr/</a>.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8863001VA	<u>3</u> /	AMP-01AX/883
5962-8863001VKA	<u>3</u> /	AMP01AN/QMLV
5962-8863001VVA	24355	AMP01AD/QMLV
5962-8863001V3A	24355	AMP01ATC/QMLV
5962-8863002VA	<u>3</u> /	AMP-01BX/883
5962-88630023A	<u>3</u> /	AMP-01BTC/883
5962-8863003VKA	24355	AMP01N/QMLV
5962-8863003VVA	24355	AMP01D/QMLV
5962-8863003V3A	24355	AMP01TC/QMLV

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE number

Vendor name and address

24355

Analog Devices Route 1 Industrial Park P.O. Box 9106 Norwood, MA 02062

Point of contact: 7910 Triad Drive

Greensboro, NC 27409-9605

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.